L Number	Hits	Search Text	DB	Tim stamp
-	3367	(wiring near layer) near10 lectrode n ar10 (connect or connecting or connected or connection or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:21
-	867	(wiring near layer) near10 electrode near10 (connect or connecting or connected or connection or bump) near10 (insulation or insulating or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:21
-	137	((wiring near layer) near10 electrode near10 (connect or connecting or connected or connection or bump) near10 (insulation or insulating or dielectric)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:22
-	16	((wiring near layer) near10 electrode near10 (connect or connecting or connected or connection or bump) near10 (insulation or insulating or dielectric)).clm. and solder.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:25
-	137	((wiring near layer) near10 electrode near10 (connect or connecting or connected or connection or bump) near10 (insulation or insulating or dielectric)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:25
-	63	((wiring near layer) near5 electrode near5 (connect or connecting or connected or connection or bump) near5 (insulation or insulating or dielectric)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:26
-	63	(electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump) near5 (insulation or insulating or dielectric)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:26
-	1	(electrode near5 (wiring nea layer) near5 (connect or connecting or connected or connection or bump) near5 (connection near member)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:27
-	4	(electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump) near5 (connection near (member or structure))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:27
-	313	(electr de near5 (wiring near layer) near5 (c nnect r connecting or connected or conn cti n r bump)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:27

		47	(electrode near5 (wiring near layer) near5 (conn ct or connecting or connect d or conn cti n r bump)).clm. and (electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:28
-		3	(electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)).clm. and (electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)).ab. and solder.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:29
-		3	(electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)).clm. and solder.clm. and bump.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:29
-		20	(electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)).clm. and solder.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:30
-		49	(electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)).clm. and solder and bump and (au or gold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:31
-		48	(electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)).clm. and solder and bump and (au or gold) and (insulation or insulating or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:31
-		29	((electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)) same (insulating or insulation or dielectric)).clm. and solder and bump and (au or gold) and (insulation or insulating or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:32
-		28	((electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)) same (insulating or insulation or dielectric)).clm. and solder and bump and (au or gold) and (insulation or insulating or dielectric) and (laminate or laminated or laminating or lamination or plate r plating or plated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:32

-		14	((electrode near5 (wiring near lay r) near5 (connect r connecting or connected r connection or bump)) sam (insulating r insulation or dielectric)).clm. and solder and bump and (au or gold) and (insulation or insulating or dielectric) and (laminate or laminated or laminating or lamination or plate or plating or plated) and ((au or gold) near5 bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:39
-		3	((electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump)) same (insulating or insulation or dielectric)).clm. and solder.clm. and bump and (au or gold) and (insulation or insulating or dielectric) and (laminate or laminated or laminating or lamination or plate or plating or plated) and ((au or gold) near5 bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:40
-		6	((electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and bump and (au or gold) and (insulation or insulating or dielectric) and (laminate or laminated or laminating or lamination or plate or plating or plated) and ((au or gold) near5 bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:41
-		3	((electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and bump.clm. and (insulation or insulating or dielectric) and (laminate or laminated or laminating or lamination or plate or plating or plated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:41
-		3	((electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and bump.clm. and (insulation or insulating or dielectric).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:41
-		20	((electrode near5 (wiring near layer) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and (insulation or insulating or dielectric).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:43
-		99	((electrode near5 (wiring) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and (insulation or insulating or dielectric).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:43
-		49	((lectrode near5 (wiring) near5 (c nn ct r c nnecting or connected or c nnection or bump))).clm. and s lder.clm. and (insulati n or insulating r dielectric).clm. and bump.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:43

-		7	((lectrode near5 (wiring) n ar5 (connect or conn cting or connected or connection or bump))).clm. and s lder.clm. and (insulation or insulating or dielectric).clm. and bump.clm. and (wire near10 (plate or plating or plated or laminate or laminated or laminating or lamination))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:43
-		23	((electrode near5 (wiring) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and (insulation or insulating or dielectric).clm. and bump.clm. and (wiring near10 (plate or plating or plated or laminate or laminated or laminating or lamination))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:44
-		17	((electrode near5 (wiring) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and (insulation or insulating or dielectric).clm. and bump.clm. and (wiring near10 (plate or plating or plated or laminate or laminated or laminating or lamination)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:44
-		1	((electrode near5 (wiring) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and (insulation or insulating or dielectric).clm. and bump.clm. and (wiring near10 (plate or plating or plated or laminate or laminated or laminating or lamination)).clm. and (bump near5 (au or gold)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:44
-		4	((electrode near5 (wiring) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and (insulation or insulating or dielectric).clm. and bump.clm. and (wiring near10 (plate or plating or plated or laminate or laminated or laminating or lamination)).clm. and (bump near5 (au or gold))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:45
-		9	((electrode near5 (wiring) near5 (connect or connecting or connected or connection or bump))).clm. and solder.clm. and (insulation or insulating or dielectric).clm. and bump.clm. and (wiring near10 (plate or plating or plated or laminate or laminated or laminating or lamination)).clm. and electrode.ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:46
-		8	((electr de near5 (wiring) near5 (c nnect r c nnecting r connect d or c nnecti n r bump))).clm. and s lder.clm. and (insulati n or insulating or diel ctric).clm. and bump.clm. and (wiring near10 (plate or plating or plated or laminate or laminated or laminating or lamination)).clm. and lectrode.ab. and wiring.ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 12:46